









Material Type: 170z FR4
Layer Count: 4
Total Material Thickness: .062"
Copper Cu Weight: 1/2 plated to 1 oz outer, 1 oz inner
Surface Finish: Immersion Silver
Trace/Space Minimum: .006"
Solder Mask: 2-Sides LPI

IDColor: White

Fab Specification: IPC-600
Panel Status: New
Unplated Slots: None
Notches: None
Outline: None
Adjust masking undersize as needed for process
Allow clipping in Gerber layers
Board Outline: Reference lines for reference only
Use Gerber outline
Technical Contact: Ward Ramsdell ward@rds-or.com
Cell - 503-806-2120

LAYER STACKUP - 4 LAYER

SILKSCREEN (TOP SIDE)

SOLDERMASK (TOP SIDE)

LAYER 1 (TOP)

Hole Inside Out
No COPPER + paste

1 mil COPPER

0.062"

+/- 10%

LAYER 2

0 mil COPPER

0.062"

+/- 10%

LAYER 3

1 mil COPPER

0.062"

+/- 10%

LAYER 4 (BOTTOM)

0 mil COPPER

0.062"

+/- 10%

LAYER BOTTOM (4)

BOARD NAME: Power Distribution Gateway, High Voltage

BOARD NUMBER: RL0005 REVISION: E

PROJECT NAME: Revoluton Lighting

DESIGNER: W. Ramsdell ENGINEER:

Ramsdell Design Services, LLC

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Tualatin, OR 97062

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Component Side View





